

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-7 (canceled).

Claim 8 (currently amended): A laminated ceramic electronic component comprising:

a plurality of ceramic sheets, each including an internal conductor pattern having a first land at one end of the internal conductor pattern and a second land at the other end of the internal conductor pattern and having a via hole provided therein, the plurality of ceramic sheets being laminated to define a laminate; wherein

the via hole is filled with a conductive material;

the internal conductor patterns disposed on different ones of the plurality of ceramic sheets are electrically connected to each other through the via hole;

the first land is arranged so as to cover the via hole and the first land provided in one of the plurality of ceramic sheets is electrically connected to the second land provided in another of the plurality of ceramic sheets through the via hole provided in the one ceramic sheet; ~~and~~

~~the second land is larger than the first land~~ an area of the via hole is less than an area of the first land and an area of the second land; and

the area of the second land is greater than the area of the first land.

Claim 9 (currently amended): The laminated ceramic electronic component according to Claim 8, wherein the second land extends from a projection plane of the first land to a projection plane of the ~~coil~~ internal conductor pattern.

Claim 10 (previously presented): The laminated ceramic electronic component according to Claim 8, wherein the area of the second land is about 1.10 to about 2.25 times as wide as the area of the first land.

Claim 11 (previously presented): The laminated ceramic electronic component according to Claim 8, wherein the internal conductors included on the plurality of ceramic sheets define a spiral coil.

Claim 12 (previously presented): The laminated ceramic electronic component according to Claim 11, wherein terminal ends of the spiral coil define lead-out electrodes.

Claim 13 (previously presented): The laminated ceramic electronic component according to Claim 11, further comprising two additional ceramic sheets which do not include any internal conductors disposed therein, one of the two additional ceramic sheets being disposed on an upper surface of the laminate, and the other of the two additional ceramic sheets being disposed on a lower surface of the laminate.

Claim 14 (currently amended): A manufacturing method for a laminated ceramic electronic component, comprising the steps of:

printing an internal conductor pattern having a first land at one end of the internal conductor pattern and a second land at the other end of the internal conductor pattern on the surface of a ceramic sheet having a hole for a via hole formed therein by using a conductive material such that the first land covers the hole for via hole;

filling the conductive material in the hole for the via hole; and

laminating a plurality of ceramic sheets such that the first land in one of the plurality of ceramic sheets is electrically connected to the second land in another of the plurality of ceramic sheets through the via hole formed in the one of the plurality of ceramic sheets to obtain a laminate; wherein

~~the second land is larger than the first land~~ an area of the via hole is less than an area of the first land and an area of the second land; and
the area of the second land is greater than the area of the first land.

Claim 15 (currently amended): The manufacturing method for a laminated ceramic electronic component according to Claim 14, wherein the second land extends from a projection plane of the first land to a projection plane of the ~~coil~~ internal conductor pattern.

Claim 16 (previously presented): The manufacturing method for a laminated ceramic electronic component according to Claim 14, wherein the area of the second land is about 1.10 to about 2.25 times as wide as the area of the first land.

Claim 17 (previously presented): The manufacturing method for a laminated ceramic electronic component according to Claim 14, wherein the internal conductor pattern is printed on a ceramic sheet having the hole for the via hole formed therein and the hole for the via hole is filled with a conductive material, without providing a carrier film on a back surface of the ceramic sheet.

Claim 18 (previously presented): The manufacturing method for a laminated ceramic electronic component according to Claim 14, further comprising the step of:
arranging the internal conductors on the plurality of ceramic sheets so as to define a spiral coil.

Claim 19 (currently amended): The manufacturing method for a laminated ceramic electronic component according to Claim ~~14~~ 18, wherein terminal ends of the spiral coil define lead-out electrodes.

Claim 20 (previously presented): The manufacturing method for a laminated

ceramic electronic component according to Claim 14, further comprising the steps of:

providing two additional ceramic sheets which do not include any internal conductors printed therein;

disposing one of the two additional ceramic sheets on an upper surface of the laminate; and

disposing the other of the two additional ceramic sheets on a lower surface of the laminate.

Claim 21 (new): The manufacturing method for a laminated ceramic electronic component according to Claim 14, wherein the internal conductor pattern is printed on a ceramic sheet having the hole for the via hole formed therein, and the hole for the via hole is filled with a conductive material without providing a carrier film on a back surface of the ceramic sheet.